# CRMTGH1101A

N-Channel 105V,  $1.2m\Omega$  Typ. Power MOSFET

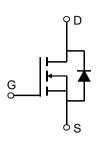
## **Description**

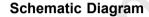
#### **Features**

• 105V, 405A

 $R_{DS(ON)}$  Typ = 1.2m $\Omega$  @  $V_{GS}$  = 10V Advanced Split Gate Trench Technology

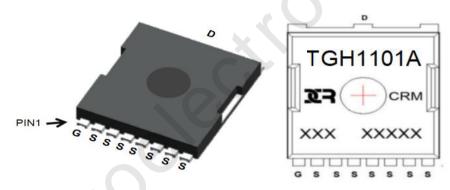
- Excellent R<sub>DS(ON)</sub> and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





# **Application**

- Load Switch
- PWM Application
- Power Management



**Marking and Pin Assignment** 

#### **Package Marking and Ordering Information**

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMTGH1101A	CRMTGH1101A	TOLL	TAPING	13"	2000	10000

#### **Absolute Maximum Ratings** (@ T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
$V_{DS}$	Drain-to-Source Voltage		105	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> = 25°C	405	Α
		T <sub>C</sub> = 100°C	243	А
I <sub>DM</sub>	Pulsed Drain Current (1)		1620	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (2)		729	mJ
$P_{D}$	Power Dissipation	T <sub>C</sub> = 25°C	521	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.24	°C/W
T <sub>J</sub> , T <sub>STG</sub>	Junction & Storage Temperature Range		-55 to 150	°C



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#### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Char	acteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	105	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 105V, V <sub>GS</sub> = 0V	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.4	2.7	3.6	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A	-	1.2	1.56	mΩ
<b>Dynamic</b>	Characteristics			<u></u>		
C <sub>iss</sub>	Input Capacitance		-	8771	-	pF
$C_{oss}$	Output Capacitance	$V_{GS} = 0V, V_{DS} = 50V,$ f = 100KHz	-	3653	-	pF
$C_{rss}$	Reverse Transfer Capacitance	1 – 100KHZ	<b>.</b> - \	89	-	pF
$Q_g$	Total Gate Charge		-	160	-	nC
$Q_gs$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 50V, I_{D} = 100A$	_	55	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge	V <sub>DS</sub> = 30V, I <sub>D</sub> = 100A	-	38	-	nC
Switchin	g Characteristics					
t <sub>d(on)</sub>	Turn-On DelayTime		-	30	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	80	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 100A$ , $R_{GEN} = 3\Omega$	-	82	-	ns
$t_{f}$	Turn-Off Fall Time		-	95	-	ns
Orain-So	urce Diode Characteristics and M	Max Ratings				
I <sub>s</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	405	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	1620	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 4004 1777 40047	-	10000	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 100A$ , di/dt = 100A/us	-	180	-	nC

Notes:

<sup>1.</sup> Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

<sup>2.</sup>  $E_{AS}$  condition: Starting  $T_J$ =25°C,  $V_{DD}$ =50V,  $V_G$ =10V,  $R_G$ =25ohm, L=0.5mH,  $I_{AS}$ =54A

<sup>3.</sup> Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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## **Test Circuit**

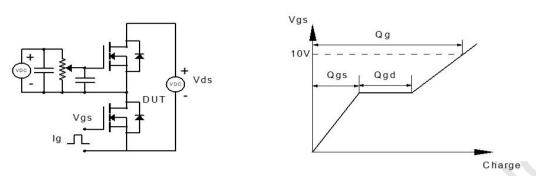


Figure 1: Gate Charge Test Circuit & Waveform

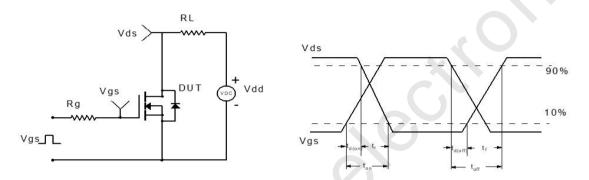


Figure 2: Resistive Switching Test Circuit & Waveform

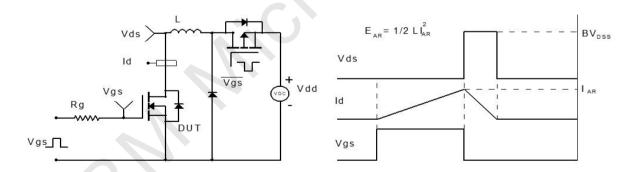


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

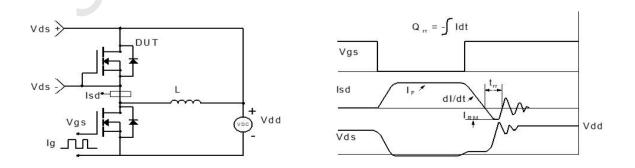
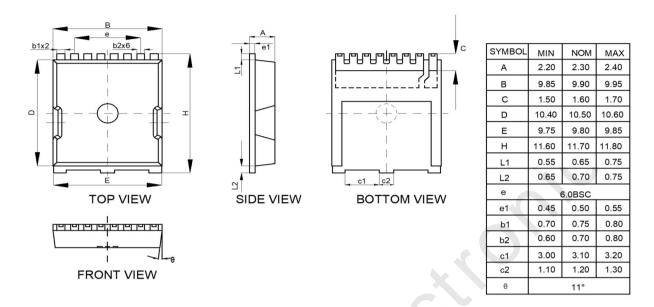


Figure 4: Diode Recovery Test Circuit & Waveform

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## Package Mechanical Data(TOLL)



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# **Contact information**

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